


101. The semiconductor device as claimed in claim 88, further comprising a heat radiating member provided on a back surface of the semiconductor element opposite to the surface thereof on which the protruding electrodes are provided.

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cancel
 102. The semiconductor device as claimed in claim 88, wherein the sealing resin used in the resin sealing step comprises a plurality of sealing resins having different characteristics.--

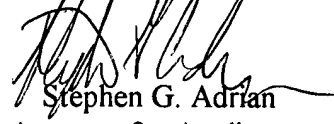
REMARKS

The above amendments are made to place the application in better condition for examination. Prompt and favorable action is earnestly solicited.

In the event that this paper is not timely filed, Applicants respectfully petition for an appropriate extension of time. The fees for such an extension or any other fees which may be due with respect to this paper, may be charged to Deposit Account No. 01-2340.

Respectfully submitted,

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Attachment: Amendment Transmittal Letter

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